ABSTRACT

INTEGRATED CIRCUIT PACKAGE SYSTEM WITH DUAL CONNECTIVITY

An integrated circuit package system includes: forming a die-attach paddle, a terminal pad, and an external interconnect with the external interconnect below the terminal pad; connecting an integrated circuit die with the terminal pad and the external interconnect; and forming an encapsulation, having a first side and a second side at an opposing side to the first side, surrounding the integrated circuit die with the terminal pad exposed at the first side and the external interconnect extending below the second side. (Fig. 2)